L Number	Hits	Search Text	DB	Time stamp
1	403	63/32.ccls.	USPAT;	2004/05/03 13:53
			US-PGPUB;	
			EPO; JPO;	
		•	DERWENT;	
			IBM_TDB	
-	286	428/28.ccls.	USPAT;	2002/06/18 13:41
		•	US-PGPUB;	
		· ·	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4	428/28.ccls. and magnet\$4	USPAT;	2002/06/18 13:42
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
-	364	63/32.ccls.	USPAT;	2002/06/18 14:23
			US-PGPUB;	
	-		EPO; JPO;	,
			DERWENT;	
			IBM_TDB	
-	57	63/32.ccls. and layer\$3	USPAT;	2002/06/18 16:35
		·	US-PGPUB;	
			EPO; JPO;	
_			DERWENT;	
			IBM_TDB	
-	3	4490440.pn.	USPAT;	2002/06/18 15:12
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	0	GB2083842A.pn.	USPAT;	2002/06/18 15:12
			US-PGPUB;	
.			EPO; JPO;	
			DERWENT;	
	_	0.000000101	IBM_TDB	
-	0	GB2083842A	USPAT;	2002/06/18 15:13
			US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
	,	OD 2002040 A 4:4	IBM_TDB	
-	1	GB-2083842-A.did.	USPAT;	2002/06/18 15:13
			US-PGPUB;	
. !			EPO; JPO;	
			DERWENT;	
_	0	(63/32.ccls. and layer\$3) and strike	IBM_TDB	2002/06/49 40:04
	9	(00/02.0013. and layerpa) and strike	USPAT;	2002/06/18 16:01
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	1	63/32.ccls. and strike	USPAT;	2002/06/18 16:01
	·	osocios and samo	US-PGPUB;	2002/00/10 10:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	86392	CVD	USPAT;	2002/06/18 16:04
			US-PGPUB;	2002/00/10 10:04
			EPO; JPO;	
			DERWENT;	
	·	•	IBM_TDB	
-	6925	CVD and diamond\$2	USPAT;	2002/06/18 16:04
		·	US-PGPUB;	_552.56716 10.04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
·	-,		IDINI_I DR	

- 5039 (CVD and diamond\$2) and layer USPAT; 2002 US-PGPUB; EPO; JPO;	2/06/18 16:08
EPO: JPO:	
DERWENT;	
- 4306 ((CVD and diamond\$2) and laver) and substrate\$2 IBM_TDB USPAT: 2002	1/00/40 40:40
- 4306 ((CVD and diamond\$2) and layer) and substrate\$2 USPAT; US-PGPUB;	2/06/18 16:10
EPO; JPO;	
DERWENT;	
IBM_TDB	
	2/06/18 16:20
(gem\$7 or jewelry) US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
	2/06/18 16:20
US-PGPUB;	
EPO; JPO;	
DERWENT;	
- 4964 (silicon and diamond) and wafer USPAT 2002	1/00/40 40:04
- 4964 (silicon and diamond) and wafer USPAT; 2002	2/06/18 16:21
EPO; JPO;	
DERWENT;	
IBM_TDB	
	2/06/18 16:23
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM_TDB	
	/06/18 16:23
	/06/18 16:26
	/06/18 16:28
	2/06/18 16:36
US-PGPUB; EPO; JPO;	
DERWENT;	÷
IBM_TDB	
	/06/18 16:36
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM_TDB	
	/06/18 17:02
US-PGPUB;	
EPO; JPO;	
DERWENT;	
- 2 (corundum near3 layer) and CVD IBM_TDB USPAT; 2002	/06/18 17:02
US-PGPUB;	700/10 17.02
EPO; JPO;	
DERWENT;	
- 80 CVD and corundum USPAT 2002	100146 1= ==
-   80   CVD and corundum   USPAT;   2002   US-PGPUB;	/06/18 17:03
EPO; JPO;	
DERWENT;	
IBM TDB	
- 23   ("Re29420"   "Re31526"   "Re32111"   "3736107"   "3836392"     USPAT   2002	/06/18 17:15
"3837894"   "3885063"   "3917473"   "3955038"   "3977061"   "4018634"   "4035544"   "4460043"   "44180400"   "4330530"	
"4018631"   "4035541"   "4169913"   "4180400"   "4239536"   "4268569"   "4399168"   "4463062"   "4474849"   "4619866"	
"4714660"   "4749630"   "4984940").PN.	
- 4 ("3412575"   "3515459"   "3959527"   "4094575").PN. USPAT 2002.	/06/18 17:22
- 6 4725511.URPN. USPAT 2002	/06/18 17:22
- 13 3539379.URPN. USPAT 2002	/06/18 17:26

-	56	(corundum and CVD) and coating	USPAT;	2002/06/18 17:30
		, -	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	4725511.pn.	USPAT;	2003/05/07 15:49
			US-PGPUB;	
		,	EPO; JPO;	
			DERWENT;	
		4705544 LIDDN	IBM_TDB	0000/05/07 45-44
-	6	4725511.URPN.	USPAT	2003/05/07 15:41
-	6	4725511.URPN.	USPAT	2003/05/07 15:41
-	43	428/620.ccls. and (picture or image)	USPAT;	2003/05/07 15:50
	ļ		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	4	("3412575"   "3515459"   "3959527"   "4094575").PN.	USPAT	2003/05/07 15:51
	10	4604329.URPN	USPAT	2003/05/07 15:51
_	11	("4512848"   "4604329"   "4634148"   "4971646"   "5190318"	USPAT	2003/05/07 15:57
		"5234537"   "5267753"   "5509553"   "5509692"   "5636874"	00.70	2000/00/01 10:01
		"5660738").PN.		